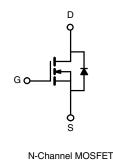
# N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	100			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0030			
I <sub>D</sub> (A) <sup>a</sup>	180			
Configuration	Single			

#### FEATURES

- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 %  $\rm R_g$  and UIS Tested





<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	100	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20			
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	- I <sub>D</sub>	180			
	T <sub>C</sub> = 125 °C		140			
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	180	A		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	680			
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	73			
Single Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	266	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	PD	375	W		
	T <sub>C</sub> = 125 °C	۲D	125			
Operating Junction and Storage Temperature Range	e	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	C°		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.6	0/10	

#### Notes

- a. Base on Tc = 25°C.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.





PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static					. <u> </u>			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0, I_D = 250 \ \mu A$		100	-	-	v	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2.5	3.0	3.5		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	1		
	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 100 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	$V_{DS} = 100 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	500		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A	-	0.0030	-	Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	-	0.0064	-		
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	-	0.0080	-		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		-	82	-	S	
Dynamic <sup>b</sup>	·	•						
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	5780	7230	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	3070	3840		
Reverse Transfer Capacitance	C <sub>rss</sub>			-	305	385		
Total Gate Charge <sup>c</sup>	Qg	V <sub>GS</sub> = 10 V	$V_{DS} = 50 \text{ V}, \text{ I}_{D} = 70 \text{ A}$	-	125	190	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	28	-		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	46	-		
Gate Resistance	Rg	f = 1 MHz		1.6	3.3	5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$\label{eq:V_DD} \begin{array}{l} V_{\text{DD}} = 50 \; V, \; R_{\text{L}} = 0.7 \; \Omega \\ I_{\text{D}} \cong 70 \; A, \; V_{\text{GEN}} = 10 \; V, \; R_{\text{g}} = 1 \; \Omega \end{array}$		-	16	25	ns	
Rise Time <sup>c</sup>	tr			-	110	165		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	40	60		
Fall Time <sup>c</sup>	t <sub>f</sub>			-	12	20		
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>				·			
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0		-	0.9	1.5	V	

Notes

a. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

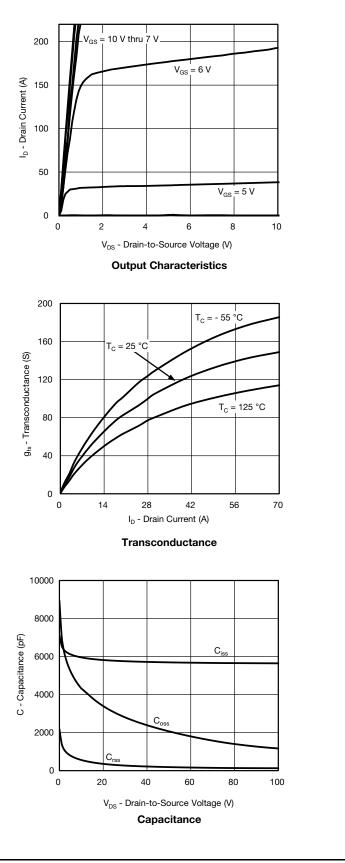
c. Independent of operating temperature.

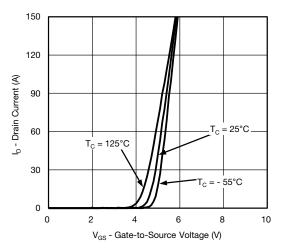
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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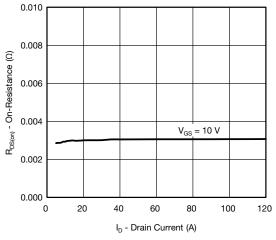


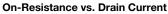
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

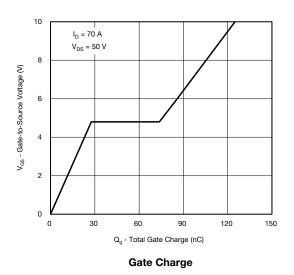




**Transfer Characteristics** 

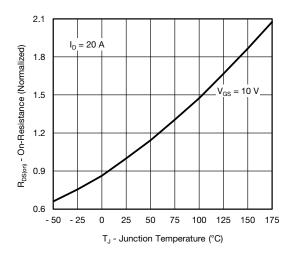




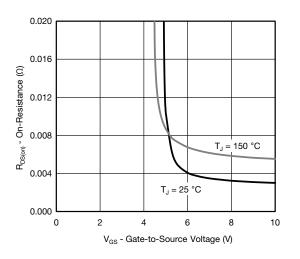




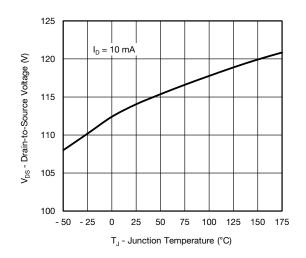
#### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



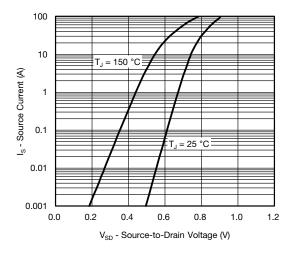
**On-Resistance vs. Junction Temperature** 



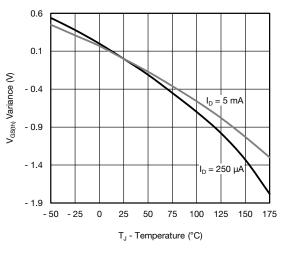
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



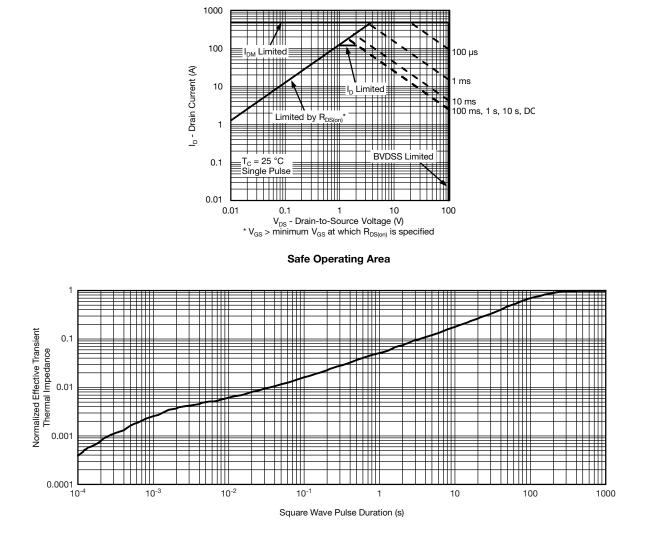
Source Drain Diode Forward Voltage



**Threshold Voltage** 



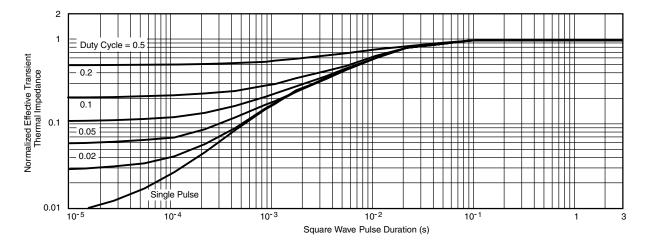
### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



#### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

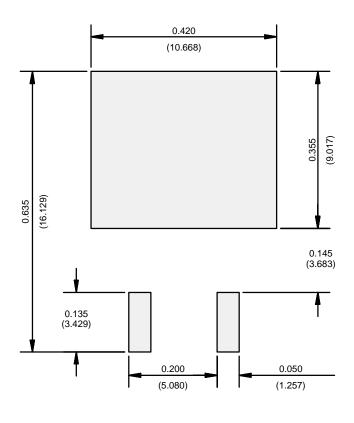
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



## **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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